

# Data and Facts

## 2011/12

### SMT Assembly

|                              |                               |
|------------------------------|-------------------------------|
| Maximum output:              | 1500 million assemblies p. a. |
| Minimum assembly dimensions: | Type 0201                     |
| Maximum assembly dimensions: | 55 mm <sup>2</sup>            |
| Fine pitch placement:        | To 0.3 mm                     |
| Circuit board dimensions:    | Max. 610 mm x 460 mm          |

#### Reflow:

- Vapour phase reflow
- Convection reflow

All fully automated reflow processes performed in a controlled nitrogen atmosphere (protective gas) and are available as leaded and unleaded processes.

### THT Assembly

|   |                             |
|---|-----------------------------|
| Maximum assembly output:                            | 80 million assemblies p. a. |
| Automated assembly preparation                      |                             |
| Semi-automatic assembly with laser assembly benches |                             |
| Double wave soldering                               |                             |
| Selective soldering                                 |                             |
| Board dimensions:                                   | Max. 650 mm x 450/500 mm    |

All fully automated soldering processes performed in a controlled nitrogen atmosphere (protective gas) and are available as leaded and unleaded processes.

### PCB Protection

|  |                 |
|--|-----------------|
| Selective coating systems with conveyor oven                                       | 400 mm x 500 mm |
| Fully automated PCB encapsulation ("Macromelt") using hot melt moulding technology |                 |

### Cable Assembly

|  |  |
|--|--|
| Fully automated single strand production                       |  |
| Semi-automatic cable production                                |  |
| IDC technology   |  |
| Crimping technology  |  |
| Soldering technology   |  |
| Semi and fully automated adhesive and encapsulation technology |  |

### Testing

|   |  |
|---|--|
| ▪ In-circuit-testing                      | ▪ Fully automated X-ray testing                                |
| ▪ Functional testing                      | ▪ Automatic visual inspection                                  |
| ▪ Climatic testing                        | ▪ Combined testing   |
| ▪ Burn-In testing                         | ▪ Safety category testing                                      |
| ▪ Run-In testing                          | ▪ Custom testing   |
| ▪ High voltage testing                    | ▪ Polished section analysis for soldered and crimp connections |
| ▪ Cable testers                           |  |
| ▪ Sequential manufacturing testing system |  |

### Certification

|                   |                |
|-------------------|----------------|
| ▪ DIN EN ISO 9001 | ▪ DIN EN 13485 |
| ▪ DIN EN 14001    | ▪ TS 16949     |

### Good partnership counts

Good, reliable partners and suppliers are key factors that help us to maintain our competitive edge. Here is a selection of our partners in the field of machinery and equipment:

